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SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Wayne Tseng	12/24/2008

RECEIVING PARTY DATA

Name:	VIA Technologies Inc.	
Street Address:	8F, No. 535, Chung-Cheng Rd., Hsin-Tien City	
City:	Taipei Hsien	
State/Country:	TAIWAN	

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	12346800	

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Total Attachments: 2 source=548086#page1.tif source=548086#page2.tif

> PATENT REEL: 022042 FRAME: 0318

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CH \$40.00

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):				
Name:	Wayne Tseng	Nationality: R.O.C.		
Hereby sells, as	ssigns and transfers to			
ASSIGNEE(S)):			
Name:	VIA Technologies Inc.			
Address:	: 8F, No. 535, Chung-Cheng Rd., Hsin-Tien City, Taipei Hsien 231, Taiwan, R.O.C.			
	sors and assignees of the ASS provements which are disclosed	IGNEE the entire right, title, and interest in and to I in the invention entitled:		
"Seria	1 Interface Device Buil	t-In Self Test"		
Which is foun	nd in :			
(a)	U.S. patent application execute	ed on even date		
(b)	U.S. patent application execut	ed on		
(c)	U.S. application serial no			
(d) 1	patent no.	issued		

PATENT REEL: 022042 FRAME: 0319 and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this DEC 2 4 2008 (Date of signing). (新發明人務坐發著上列目期:)

(Type name of inventor)

Wayne Tseng

Assignment, Page 2 of 2

F#NPO-P0002E-US1 DSB0-097U029249

NPO#VIA-P0166-USA:4 CUST#VIT04-0300-US

RECORDED: 12/30/2008